

Final Product Change Notification

201706005F01

Issue Date: 19-May-2018
Effective Date: 17-Aug-2018

Here's your personalized quality information concerning products Digi-Key purchased from Nexperia.
 For detailed information we invite you to view this notification online



Change Category

- | | | | | |
|--|--|--|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input checked="" type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input checked="" type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |

Change of die design, bond wire Au to Cu, mold compound and leadframe for PMV250EPEA

Details of this Change

Shrink of die pitch size for ssMOS type PMV250EPEA in SOT23 package. Furthermore the bond wire material will be changed from gold (Au) to copper (Cu) and a new mold compound and lead frame supplier will be introduced. Reliability qualification and full electrical characterization over temperature have been performed. No change on thermal behavior or mechanical dimensions. Electrical parameters remain unchanged (in specification and with the same distribution).

For details please see the SQR enclosed to this PCN.

Why do we Implement this Change

To increase flexibility and production efficiency at the assembly site. Nexperia continues to introduce copper wire for plastic SMD packages, aligning with world technology standards. Copper wire shows enhanced mechanical properties.

Identification of Affected Products

Changed products can be identified by date code after implementation.

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 01-Oct-2018

Impact

no impact to the product's functionality anticipated.

No impact to the products' functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Related Notifications

Notification	Issue Date	Effective Date	Title
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201706005F0119	May-2018	17-Aug-2018	Change of die design, bond wire Au to Cu, mold compound and leadframe for PMV250EPEA
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Timing and Logistics

Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 18-Jun-2018. Lack of acknowledgement of the PCN constitutes acceptance of the change.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact Nexperia "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

e-mail address DiscrQA.Helpdesk.GA-Products@nexperia.com

At Nexperia B.V. we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

About Nexperia B.V.

We at Nexperia are the efficiency semiconductor company. We deliver over 70 billion products a year and as such service thousands of global customers, both directly and through our extensive network of channel partners. We are at the heart of billions of electronic devices in the Automotive, Mobile, Industrial, Consumer, Computing, and Communication Infrastructure segments.

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Nexperia |

Nexperia B.V.

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Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Outline	Package Name	Status	Product Line
PMV250EPEAR	934067624215	PMV250EPEA	small signal MOSFET	SOT23	TO-236AB	RFS	MOS Discretes